

Thermal Technology Development for the ARTEMIS Initiative

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OBJECTIVE: Develop an *autonomous <u>lunar night survivable</u> thermal architecture* without radioisotopes to enhance JPL's lunar instrument implementation capabilities with a science focus on *magnetometers, seismometers, and IR spectrometers*.

FY19/Q4 – Early Start to FY20 Work Plan ARTEMIS was originally planned as a 3-year JPL Strategic R&TD Program that was intended to start in FY20. Program granted approval to start early (in FY19-Q4). <u>Goal for FY19-Q4 was to complete</u> preliminary drawings for the four subscale testbeds defined in FY20 description to the right and below.

FY20 – Technology Development Develop/evaluate ARTEMIS thermal architecture key elements through 4 subscale testbeds: (1) Dual Thermally-Switched Enclosures; (2) Parabolic Reflector Radiators (PRRs); (3) High Performance MLI; (4) High Performance Thermal Isolators. Also, start to gather requirements on 3 instrument types.

FY21 – Small Scale Demonstration Validate ARTEMIS thermal architecture at small scale by combining FY20 subscale testbed elements into an integrated full-up testbed and finalize gathering requirements on 3 instrument types. Initiate design of full scale ARTEMIS demo unit w/ JPL SVH magnetometer, deployable boom,

FY22 – Full Scale Demonstration Validate ARTEMIS thermal architecture at full scale by completing design of full scale demo unit, which includes FY21 small scale system testing and instrument requirements gathering results. Build demo unit that includes a JPL SVH magnetometer and deployable boom. Carry out TVAC test demo.

ARTEMIS Technology Development Focus

ARTEMIS AUTONOMOUS THERMAL ARCHITECTURE

HOW IT WORKS: During Lunar Day, heat from Instruments conducted along the thermal path $H \rightarrow TS1 \rightarrow STP1 \rightarrow EH \rightarrow TS2 \rightarrow STP2 \rightarrow RAD$ with TS1 and TS2 both ON. As Lunar Night ensures, TS2, TS1 turn OFF autonomously at 273 K, drastically reducing heat loss. Thermal Switches are JPL Reverse-Operation Differential Thermal Expansion (DTE) Thermal Switches (5 W/K ON, 0.002 W/K OFF, 2500:1 ON/OFF). To validate architecture, series of 4 TESTBED subtasks in concert with an INSTRUMENT THERMAL NEEDS subtask planned for FY20.

Areas and Key Measurable Metrics (KMM) **Dual Thermally-Switched Enclosure** KMM \rightarrow Lunar Heat Loss Flux < 5 W/m² **Affordable Parabolic Reflector Radiator** KMM \rightarrow Sink Temp on Lunar Surface < 280 K **High Performance Multi-Layer Insulation** KMM \rightarrow Effective Emissivity < 0.01 **High Performance Thermal Isolator** KMM \rightarrow Conductance < 0.001 W/K **Science Instrument Requirements**

KMM \rightarrow 50% defined by FY20, 100% by FY21



Subtask	Concept	Design	CAD	Drawings		KMM Validation
1→ Develop subscale assembly of ARTEMIS architecture; design and build testbed to show performance.	SHROUD (LUNAR ENVIRONMENT)	 SIZING (IH, EH, SHROUD) 127, 254, 381 mm x 6 mm Al cubes 305 mm x 305 mm x 3 mm Al radiator LUNAR NIGHT SIMULATION TCP = 90 K, TIH > 240 K (survival heater) LUNAR DAY SIMULATION TCP = 280 K (PRR assumed), QIH = 5-8 W THERMAL SWITCH JPL RevOp. DTE Design-2 (Ultem 1000/Alum) THERMAL STRAP Graphite foil based, 2 W/K (Thermotive) 		 INTERNAL HOUSING (IH) 20019541 EXTERNAL HOUSING (EH) 20019542 LUNAR SHROUD (LS) 20019543 THERMAL SWITCH 20019547->20019551 THERMAL STRAP, RADIATOR 20019546, 20019554 OVERALL ASSEMBLY 20019545 		Heat loss flux < 5 W/m ² , means 127 mm IH cube will require < 0.5 W to stay warm in the cold case. With conventional ε *=0.02 MLI, T _{IH} must be > 253 K.
2→ Develop design and fabrication method for low cost PRRs; design, build testbed to show performance.	1-CELL PRR (DEPTH D)N-CELL PRR testbedHImage: Cold Plate Image: Cold Plate 	SIZING (IR PLATE, PRR, LS) - IR PLATE (381 mm into page x 508 mm) - PRR (N=10, D / H / W = 127 / 12.7 / 6.35 mm) - LS (approx. 500 mm x 600 mm x 200 mm) LUNAR NIGHT SIMULATION - NOT REQUIRED LUNAR DAY SIMULATION - TCP = 90-280 K - TIRP = 373 K - QPRR = 0-2 W - QIRP = 200 W (approx.)		 PRR 10-CELL RADIATOR - 20019931 PRR 10-CELL REFLECTO - 20019932 PRR TESTBED: IR PLAT - 20019934 PRR TESTBED: LUNAR S - 20019935→20019938 PRR TESTBED: OVERAL - 20019939 	R ARRAY OR ARRAY E SHROUD L ASSEMBLY	<i>Rad. sink temp < 280 K</i> is applicable when lunar shroud temperature is set to 90 K. With lunar shroud at 280 K, radiative sink temp will exceed 280 K.
3 \rightarrow Develop design and fabrication method for low ε^* MLI; design and build testbed to show performance.	$\begin{array}{l} \label{eq:spaces} & \text{``SPACERLESS'' MLI DONCEPT'' TESTBED''} \\ \hline \\ $	 SIZING (DEMO MODEL, TESTBED) INNER FRAME, HSG (IF, IH) 87 mm, 127 mm OUTER FRM, HSG (EF, EH) 165 mm, 384 mm KEVLAR CABLES CORNER CABLE 62 mm x 8 PERIPHERAL CABLE #1 99 mm x 12 (inner) PERIPHERAL CABLE #2 111 mm x 12 PERIPHERAL CABLE #3 123 mm x 12 PERIPHERAL CABLE #4 135 mm x 12 PERIPHERAL CABLE #5 147 mm x 12 (outer) 		 SPACERLESS MLI (S-MLI) DEMO MODEL - 20019555 S-MLI TESTBED: IH + KEVLAR BRKTS - 20019561*, 20019562* S-MLI TESTBED: EH + KEVLAR BRKTS - 20019563*, 20019564* S-MLI TESTBED: LS + KEVLAR BRKTS - 20019565*, 20019566* S-MLI TESTBED: OVERALL ASSEMBLY - 20019560* * Drawing number assigned, drawing incomplete 		MLI $\varepsilon^* < 0.01$ will require test setup w/ just a few wires to minimize parasitic heat gains/leaks so that the relation $\varepsilon^* = Q/(T_i^4 - T_o^4)$ is the sole governing eqn.
4→ Develop design and fabrication method for low G isolators; design, build testbed to show performance.	ISOLATOR OPTIONS UTLEM FLEXURE ULTEM + KEVLAR \overbrace{O}	 SIZING (STRUCTURAL FEM) SUPPORT FOR 10 KG INSTRUMENT PKG. FOUR ISOLATORS PER INSTRUMENT PKG. PACKAGE DIMENSIONS 300 x 200 x 150 mm 	<image/>	 POLYMER FLEXURE ISO - 20019553-1 POLYMER KEVLAR CAB - 20019951* ISOLATOR TESTBED: CO - 20019952* ISOLATOR TESTBED: Q- - 20019953* ISOLATOR TESTBED: OV - 20019954* * Drawing number assigned, drawing 	LATOR LE ISOLATOR OLD SHROUD METER /ERALL ASSY	Isolator G < 0.001 W/K will require test setup with Q-meter that minimizes parasitic heat gains/leaks so that G = Q/DT is the sole governing equation.
Instrument Implementation		DTE Thermal Switching		Future Challenges		
TYPECHALLMAGNETOMETERExternal Boom Boom Deploys External FiberSEISMOMETERRigid Link to O High Data Rat High Duty CyceIR SPECTROMETERHigh Power (O High Data Rat Apertures, External Sector)	LENGESCANDIDATESnSVHmentSI-CopticsOthersCarrierSPumage: see see see see see see see see see s	At 300 K, ROD Stretched for High DISC-CYL "ON" Force At < 273 K, CYL Differentially Contracts Causing "OFF" G RADIATOR I/F HIGH k DISC HIGH K DISC HIGK K DISC HIGH K DISC HIGH K DISC HIGK K DISC HIGH K DISC HIG	 Reverse-Operation DTE Thermal Switch Prototypes and Exaggerated Gap on LN2-Exposed Demo Unit Image: Structure of the structure of the	BATTERIES RADIO/COMM→ Packaging Enough for Overnight Ops/Survival → Internals + Antenna for Carrier Independence → Processing Capability for Carrier Independence → Processing Capability for Carrier Independence → IR Spectrometers May Need 2-Axis Gimbal → Multi-Instrument Capability Sought by NASA → Use 100 K Nighttime Temps to Eliminate CCs → Combo Unit with Switch for 20000:1 ON/OFF → Extended Stroke Thermal Switch (see Demo Unit)		
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ARchitecture for **T**hermal **E**nclosure of **M**oon **I**nstrument **S**uites









